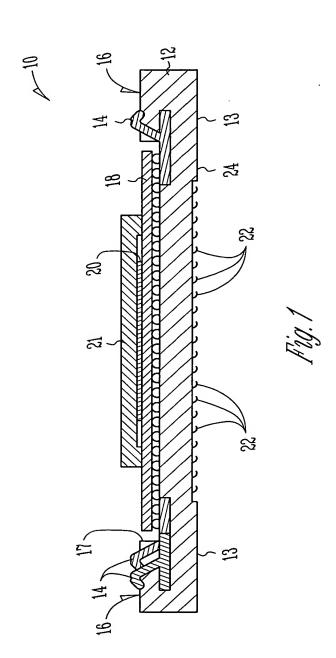
INVENTOR'S NAME: Donald T. Tran

SERIAL NO.: 10/810,957 DOCKET NO.: 884.B83US1

1/5



INVENTOR'S NAME: Donald T. Tran

SERIAL NO.: 10/810,957 DOCKET NO.: 884.B83US1

2/5

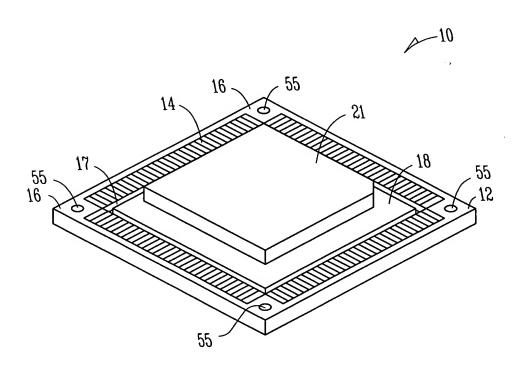
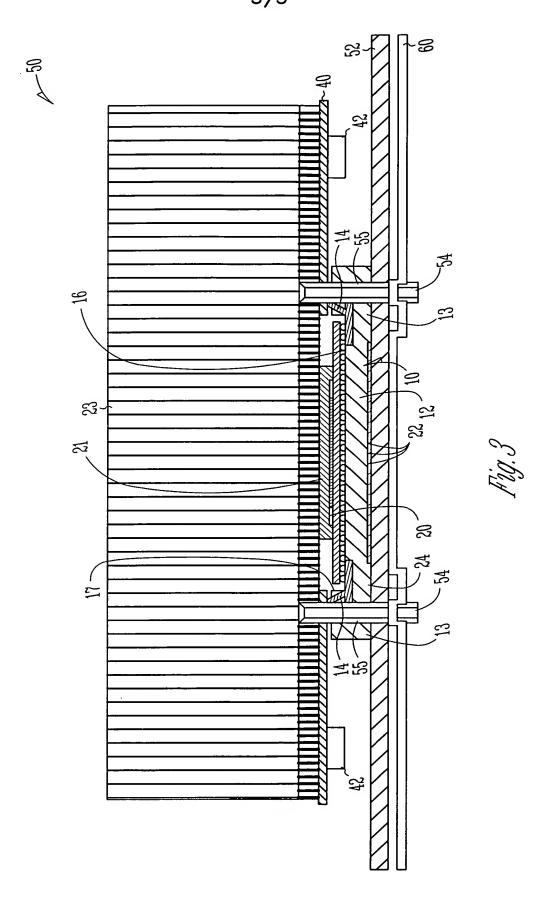


Fig.2

TITLE: ELECTRONIC ASSEMBLY WITH INTEGRATED IO AND POWER CONTACTS $% \left(1\right) =\left(1\right) \left(1\right) \left($

INVENTOR'S NAME: Donald T. Tran
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INVENTOR'S NAME: Donald T. Tran

SERIAL NO.: 10/810,957 DOCKET NO.: 884.B83US1

4/5

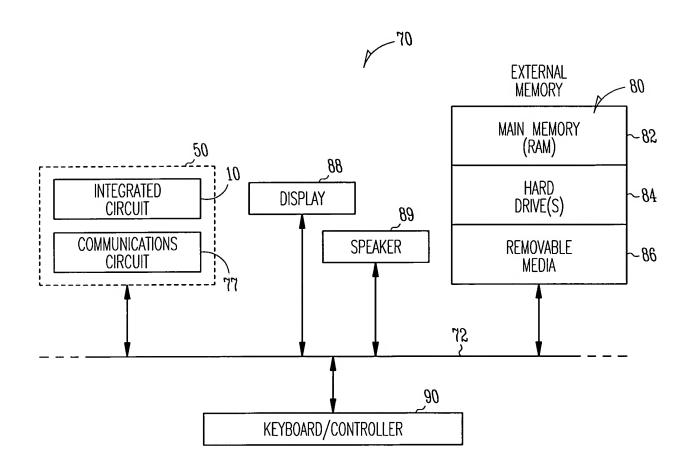


Fig. 4

INVENTOR'S NAME: Donald T. Tran

SERIAL NO.: 10/810,957 DOCKET NO.: 884.B83US1

5/5

REPLACEMENT SHEET

__100 110 ATTACHING A DIE TO A SUBSTRATE 150 ATTACHING THE SUBSTRATE TO AN UPPER SURFACE OF A BASE -SURFACE MOUNTING THE SUBSTRATE TO THE BASE -MOUNTING THE SUBSTRATE WITHIN A RECESS IN THE BETWEEN THE UPPER SURFACE OF THE BASE 130 FNGAGING POWFR CONTACTS THAT EXTEND FROM THE UPPER SURFACE OF THE BASE WITH A DAUGHTERBOARD THAT INCLUDES A VOLTAGE SOURCE 140 SUPPLYING POWER FROM THE VOLTAGE SOURCE TO THE DIE USING THE POWER CONTACTS 150 ATTACHING A MOTHERBOARD TO A BOTTOM SURFACE OF THE BASE 160 SECURING THE MOTHERBOARD AND THE DAUGHTERBOARD TO A CHASSIS -COMPRESSING THE BASE, THE SUBSTRATE AND THE DIE -MOTHERBOARD AND THE DAUGHTERBOARD 170 ATTACHING A HEAT SPREADER TO THE DIE 180 ATTACHING A HEAT SINK TO THE HEAT SPREADER

Fig. 5